

FORM PTO-1449
(REV. 7-80)US. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICEATTY. DOCKET NO.
RD-26,616

SERIAL NO.

INFORMATION DISCLOSURE STATEMENT BY APPLICANT
LIST OF ITEMS

Applicant

RAYMOND A. FILLION, ET AL

Filing Date

Group



U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
<i>W</i>	AA 4783695	11/8/88	EICHELBERGER, ET AL			
<i>W</i>	AB 4894115	1/16/90	EICHELBERGER, ET AL			
<i>W</i>	AB 4933042	6/12/90	EICHELBERGER, ET AL			
<i>W</i>	AC 5055907	10/8/91	JACOBS			
<i>W</i>	AD 5149662	9/22/92	EICHELBERGER			
<i>W</i>	AE 5161093	11/3/92	GORCZYCA, ET AL			
<i>W</i>	AF 5366906	11/22/94	WOJNAROWSKI, ET AL			
<i>W</i>	AG 5367763	11/29/94	LAM			
<i>W</i>	AH 5353498	10/11/94	FILLION, ET AL			
<i>W</i>	AI 5527741	6/18/96	COLE, ET AL			
	AJ					
	AK					
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	AM					
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	AQ					
	AR					
	AS					
	AT					
	AU					
	AV					

OTHER INFORMATION (Including Author, Title, Date, Pertinent Pages, etc.)

<i>W</i>	BA	B. Burdick, et al, "Extension of the Chip-on-Flex Technology to Known Good Die", presented at the 5th International Conference and Exhibition on Multichip Modules, April 17-19, 1996, Denver, Co., 6 pages.
	BB	

EXAMINER

K Pearson

DATE CONSIDERED

4/24/99

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.